

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the application of:	)	
	)	Group Art Unit: 3744
CHEN et al.	)	
	)	Examiner: CIRIC, L.
Application No: 10/712,708	)	
	)	Docket No: JLINP174/TLC
Filed: November 12, 2003	)	
	)	Date: Dec 24, 2009
For: <u>HEAT DISSIPATION MODULE</u>	)	

**CERTIFICATE OF E-Filing**

I hereby certify that this paper and the documents and/or fees referred to as attached herein are  
being electronically filed with the United States Postal Service on **Dec. 24, 2009**.  
/Cyndie Lorente/

**AMENDMENT**

Honorable Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

This paper is in response to the Official Action mailed on Jan. 29, 2008.  
Notice that an RCE was filed on April 15, 2008. This is also responsive to the action  
of Nov. 30, 2009. Applicant respectfully submits comments in connection with the  
above-named application.

**Amendments to the claims** are reflected in the listing of claims which begin  
on page 2 of this paper.

**Remarks/Arguments** begin on page 6 of this paper.